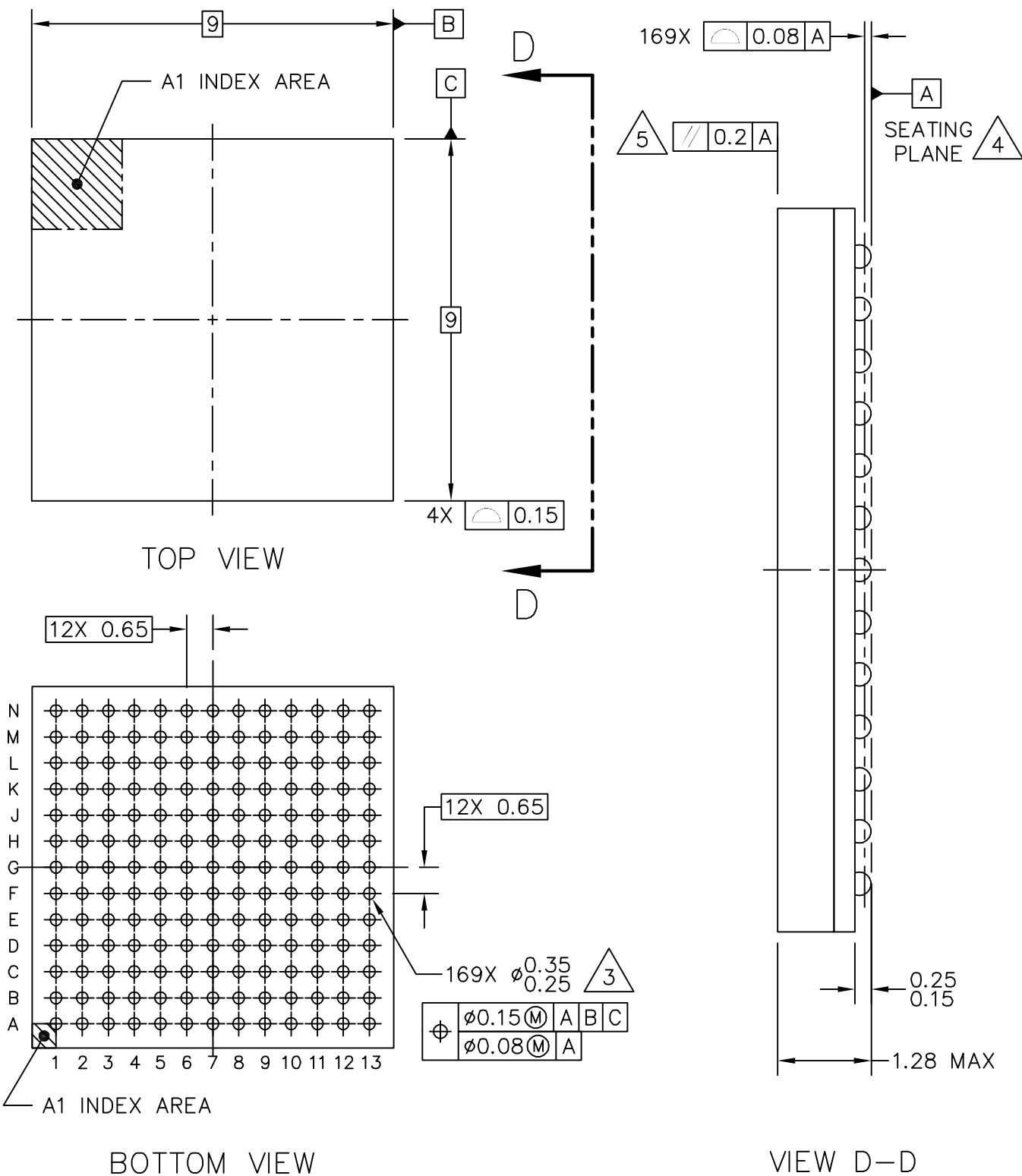




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TITLE: MAPBGA, LOW PROFILE 9 X 9 X 1.15 PKG 0.65 MM PITCH, 169 I/O	DOCUMENT NO: 98ASA00628D REV: 0	
	STANDARD: NON-JEDEC	
	29 AUG 2013	



NOTES:

- 1. ALL DIMENSIONS IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.
- 3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
- 4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- 5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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